

Electronic Instrumentation





User Manual UM4279 V1742/VX1742 32+2 Channel 12bit 5 GS/s Switched Capacitor Digitizer Rev. 8 - February 05th, 2020

Purpose of this Manual

This document contains the full hardware description of the V1742 and VX1742 CAEN digitizers and their principle of operating as Waveform Recording Digitizer (basing on the hereafter called *"waveform recording firmware"*).

The reference firmware revision is: **4.21_1.03**.

For any reference to registers in this user manual, please refer to document [RD1] at the digitizer web page.

Change Document Record

Date	Revision	Changes
-	00-06	N/A
January 27 th , 2017	07	Revised text layout. Improved text description to make it clearer.
February 05 th , 2020	08	Updated Sections: Safety Notices, Internal Components, PLL Mode, Timer Reset, Front Panel LVDS I/Os, Troubleshooting. Reviewed Sections: Data Transfer Capabilities and Events Readout, Optical Link Access, Drivers. Added Sections: Trigger Rate.

Symbols, Abbreviated Terms and Notation

ADC	Analog-to-Digital Converter
AMC	ADC & Memory Controller
DAQ	Data Acquisition
DAC	Digital-to-Analog Converter
DC	Direct Current
LVDS	Low-Voltage Differential Signal
PLL	Phase-Locked Loop
ROC	ReadOut Controller
TTT	Trigger Time Tag
USB	Universal Serial Bus

Reference Documents

- [RD1] UM5698 742 Registers Description.
- [RD2] GD2512 CAENUpgrader QuickStart Guide.
- [RD3] UM2091 CAEN WaveDump User Manual.
- [RD4] UM1935 CAENDigitizer User & Reference Manual.
- [RD5] UM4513 V1718 & VX1718 User & Reference Manual.
- [RD6] UM3236 & VX2718 User & Reference Manual.
- [RD7] UM1934 CAENComm User & Reference Manual.
- [RD8] GD5695 742 Quick Start Guide.
- [RD9] AN2086 Synchronization of CAEN Digitizers in Multiple Board Acquisition Systems.
- [RD10] AN2472 CONET1 to CONET2 Migration.
- [RD11] UM4413 A2818 Technical Information Manual.

[RD12] UM3121 - A3818 Technical Information Manual.

https://www.caen.it/support-services/documentation-area/ (login required)

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MADE IN ITALY: We remark that all our boards have been designed and assembled in Italy. In a challenging environment where a competitive edge is often obtained at the cost of lower wages and declining working conditions, we proudly acknowledge that all those who participated in the production and distribution process of our devices were reasonably paid and worked in a safe environment (while this is true for the boards marked "MADE IN ITALY", we cannot guarantee for third-party manufactures).



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1 Safety Notices

CAUTION: to manage the product, consult the operating instructions provided.



A POTENTIAL RISK EXISTS IF THE OPERATING INSTRUCTIONS ARE NOT FOLLOWED!

CAUTION: this product needs proper cooling.



USE ONLY CRATES WITH FORCED COOLING AIR FLOW SINCE OVERHEATING MAY DEGRADE THE MODULE PERFORMANCES!

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2 Introduction

The Mod. V1742 is a 1-unit wide VME 6U module housing 32+2 Channel 12 bit 5 GS/s Switched Capacitor Digitizer sections.

The input dynamic range is 1 V_{pp} (DC coupled) on single-ended MCX coaxial connectors with a 16-bit DAC on each channel to control the DC Offset (\pm 1 V range).

The digitizer is based on the Switched Capacitor Array DRS4 chip¹ (Domino Ring Sampler). This technology relies on a series of 1024 capacitors (analog memory) in which the analog input signal is continuously sampled in a circular way. The sampling frequency is 5 GHz by default and it can be programmed to 2.5 GHz, 1GHz, and 750 MHz. The analog to digital conversion is not simultaneous with the chip sampling phase, and it starts as soon as the trigger condition is met. When the trigger stops the DRS4 chip sampling (holding phase), the analog memory buffer is frozen, and the cell content is made available to the 12 bit ADC for the digital conversion. The digital memory allows to store subsequent events, even if the readout is not yet started. Moreover, since the digital memory buffers work like FIFOs, the readout activity from VME or Optical Link does not affect write operations of subsequent events.

The chip functioning has two major consequences:

- there is an unavoidable dead-time when the DRS4 chip stops its acquisition and the ADC converts the capacitances (110 μs in case only the analog inputs are digitized, 181 μs when also TRn are digitized).
- the acquisition window is fixed to 1024 samples, that in case of 5 GHz corresponds to a maximum of about 200 ns. Refer to Sec. Domino Ring Sampling.

Moreover, the trigger processing introduces a latency between the trigger arrival and the DRS4 holding phase that varies according to the trigger source. The user must consider it when choosing the proper trigger source for its setup and the type of signal. Four possible trigger sources are available:

- Software Trigger, common to all enabled groups, mainly intended for debug purposes. Refer to Sec. Software Trigger.
- External Trigger, trigger on TRG-IN connector, common to all enabled groups. The external trigger latency makes this mode difficult to use at 5 GHz, while all other frequencies can be used with no problem. Refer to Sec. External Trigger.
- 3. Fast (Low Latency) Local Trigger, trigger on TRO and TR1 connectors, common to couples of groups. This mode is called "Fast" or "Low Latency" since the trigger latency is reduced with respect to the external trigger. This trigger mode is convenient for high precision timing measurements, since the TRn can be digitized and reported in the output data to be used as time reference. Refer to Sec. Fast ("Low Latency") Trigger.
- 4. Self-trigger, common to couples of groups. For each group is possible to select combination of channels (logic OR) that provide a trigger whenever the input crosses the threshold. This mode cannot be used at 5 GHz due to the trigger latency and one of the other options must be used. Refer to Sec. Self-Trigger for additional details.

The module features the front panel CLK IN/CLK OUT connectors and an internal PLL for clock synthesis from internal/external references. V1742 supports multi-board synchronization allowing all DRS4s to be synchronized with a common clock source and ensuring Trigger Time Stamps alignment. Once synchronized, all data will be aligned and coherent across multiple V1742 boards.

By ordering options (see **Tab. 2.1**), the module is available with digital memory sizes of 128 event/ch or 1024 event/ch.

The VME interface of the module is VME64X compliant, and the data readout can be performed in several data transfer modes: BLT32, MBLT64 (up to 70 MB/s of transfer rate using CAEN Bridge), CBLT32/64, 2eVME, 2eSST (up to 200 MB/s of transfer rate). The built-in daisy chainable Optical Link, implementing CONET proprietary protocol, is able to transfer data at 80 MB/s, thus it is possible to connect up to 8 boards to a single A2818 Controller, or up to 32 to a single A3818 Controller (4-link version, see **Tab. 2.1**).

¹Designed at Paul Scherrer Institute (PSI). Detailed documentation of the DRS4 chip is available at http://drs.web.psi.ch/

Board Model	Description		
V1712	32+2 Ch. 12 bit 5 GS/s Switched-Capacitor Digitizer: 128 events/ch		
V1/42	(1kS/events), EP3C16, SE		
V/17/2D	32+2 Ch. 12 bit 5 GS/s Switched-Capacitor Digitizer: 1024 events/ch		
V1/42B	(1kS/events), EP3C16, SE		
VV1740	32+2 Ch. 12 bit 5 GS/s Switched-Capacitor Digitizer: 128 events/ch		
VX1/42	(1kS/events), EP3C16, SE		
	32+2 Ch. 12 bit 5 GS/s Switched-Capacitor Digitizer: 1024 events/ch		
VX1/42D	(1kS/events), EP3C16, SE		
Related Products	Description		
A2818	A2818 – PCI Optical Link (Rhos compliant)		
A3818A	A3818A – PCIe 1 Optical Link		
A3818B	A3818B – PCIe 2 Optical Link		
A3818C	A3818C – PCIe 4 Optical Link		
V1718	V1718 - VME-USB 2.0 Bridge		
V1718LC	V1718LC - VME-USB 2.0 Bridge (Rohs Compliant)		
VX1718	VX1718 - VME-USB 2.0 Bridge		
VX1718LC	VX1718LC - VME-USB 2.0 Bridge (Rohs Compliant)		
V2718	V2718 - VME-PCI Bridge		
V2718LC	V2718LC - VME-PCI Bridge (Rohs compliant)		
VX2718	VX2718 - VME-PCI Bridge		
VX2718LC	VX2718LC - VME-PCI Bridge		
	V2718KITLC - VME-PCI Bridge (V2718)+PCI Optical Link		
V2/18LC KIT	(A2818)+Optical Fibre 5m duplex (AY2705) (Rohs)		
	V2718KIT - VME-PCI Bridge (V2718) + PCI OpticalLink (A2818) +		
V2/18 KII	Optical Fibre 5m duplex (AY2705)		
	V2718KITB - VME-PCI Bridge (V2718) + PCIe Optical Link (A3818A) +		
V2/18 KII-B	Optical Fibre 5m duplex (AY2705)		
	VX2718KITLC - VME-PCI Bridge (VX2718)+PCI Optical Link		
	(A2818)+Optical Fibre 5m duplex (AY2705) (Rohs)		
VX2718 KIT	VX2718KIT - VME-PCI Bridge (VX2718) + PCI OpticalLink (A2818) +		
V/2/10 KH	Optical Fibre 5m duplex (AY2705)		
VX2718 KIT-B	VX2718KITB - VME-PCI Bridge (VX2718) + PCIe Optical Link (A3818A) +		
	Optical Fibre 5m duplex (AY2705)		
Accessories	Description		
A317	Clock Distribution Cable		
A317L	Clock Distribution Cable L 25 cm		
DT4700	Clock Generator		
A318	Single-Ended to Differential Clock Adapter		
A654	Single Channel MCX to LEMO Cable Adapter		
A654 KIT4	4 MCX TO LEMO Cable Adapter		
A654 KIT8	8 MCX TO LEMO Cable Adapter		
A659	Single Channel MCX to BNC Cable Adapter		
A659 KIT4	4 MCX TO BNC Cable Adapter		
A659 KIT8	8 MCX TO BNC Cable Adapter		
AI2730	Optical Fibre 30 m simplex		
AI2720	Optical Fibre 20 m simplex		
AI2705	Optical Fibre 5 m simplex		
AI2703	Optical Fibre 30 cm simplex		
AY2730	Optical Fibre 30 m duplex		
AY2720	Optical Fibre 20 m duplex		
AY2705	Optical Fibre 5 m duplex		

Tab. 2.1: Table of models and related items

3 Block Diagram



Fig. 3.1: Block Diagram

4 Technical Specifications

GENERAL	Form Factor		Weight
	1-unit wide, 60 VME64 (V1742)	and VME64X (VX1742)	520 g
		Connector	
		MCX	8 I 144
	Channels		Bandwidth
	32 channels	Full Scale Range (FSR)	500 MHz
	2 special channels (TRO, TR1)	1 V _{pp}	Offeet
ANALOG INPUT	Single ended	Absolute may analog input	Oliset
		voltage	Programmable 16-bit DAC for
	Impedance	2)/((with)/(max/2)/ar)	DC onset adjustment on each
	$Z_{in} = 50 \Omega$	3Vpp (With V _{rail} max +3V of	channel. Range: \pm 1 V
		-3V) for any DAC onset in	
		single ended configuration	
	Resolution	Compline Date	
	12 bits		
DIGITAL	Switched Conscitor Arroy	5 GS/S - 2.5 GS/S - 1 GS/S -	Dead Time (A/D Conversion)
CONVERSION	Switched Capacitor Array	0.75 GS/s SW selectable,	110 µs, analog inputs only
	(DDC4) 811 shannals with	simultaneously on each	181 μ s, digitizing TRU and TR1
	(DRS4), 8+1 Channels with	channel	
	1024 storage cells each		
ADC CLOCK	Clock source: Internal/external.	un video companyation of the main h	and dealer from internal (FO
GENERATION	On-board programmable PLL p	l (frant namel CLK IN commenter)	
	AC coupled differential input	CLK-OUT (AMP Modu II)	
	clock	DC coupled differential	
		LVDS clock output locked at	S-IN (LEMO)
	(single ended NIM/TTI	ADC sampling clock	SYNC/START
	(single ended MM) TT	1 0	front nanel digital input
DIGITAL I/O	litter < 100 ppm requested		NIM/TTI
	sitter < 100 ppin requested		$7_{in} = 50.0$
	TRG-IN (LEMO)	Trigger digital output	
	External trigger digital input		
	NIM/TTL	7 = 50.0	
	$Z_{in} = 50 \Omega$	$z_{in} = 30.32$	
	128 events/ch or 1024 events/c	h (1024 S/event) Multi-event But	ffer
	Independent read and write access; programmable event size and pre/post-trigger		
			Trigger Propagation
	Trigger Source		TRG-OUT programmable
	- Fast (Low Latency) trigger: Pi	ogrammable threshold on TRO	digital output
	and TR1 (each TRn signal drives	two 8-ch groups)	
TRIGGER	- Self-trigger: Logic OR combin	nation of channels over/under	Irigger Time Stamp
	threshold (each channel self-tri	gger drives two 8-ch groups)	30-bit counter
	- External-trigger: Common trig	ger by TRG IN connector	8.5 ns resolution
	- Software-trigger: Common tri	gger by software command	9 s range
		Timer reset by S-IN	

SYNCHRONIZATION	Clock Propagation <i>Daisy chain</i> : through CLK-IN/CLK-OUT connectors <i>One-to-many</i> : clock distribution from an external clock source on CLK-IN connector Clock Cable delay compensation	Acquisition Synchronization Sync, Start/Stop through digital I/Os (S-IN or TRG-IN input / TRG-OUT output) Data Aligment Busy/Veto management through digital I/Os (TRG-OUT/TRG-IN) or LVDS I/Os	
ADC & MEMORY CONTR.	Altera Cyclone EP3C16 (one FPGA manages 16+1 channels)		
COMMUNICATION INTERFACE	Optical Link CAEN CONET proprietary protocol Up to 80 MB/s transfer rate Daisy-chain capability	VME VME 64X compliant Data transfer mode: BLT32, MBLT64 (70 MB/s by CAEN Bridge), CBLT32/64, 2eVME, 2eSST (200 MB/s)	
LVDS I/O	16 general purpose LVDS I/O controlled by the FPGA: Busy, Data Ready, Memory full, Individual Trig-Out and other functions can be programmed. An Input Pattern from the LVDS I/O can be associated to each trigger as an event marker		
FIRMWARE UPGRADE	Supported via VMEbus/Optical Link		
SOFTWARE	General purpose C libraries, configuration tools, readout demos (Windows [®] , Linux [®] and VIEW [™] support) WaveDump readout software with C source files and VS poject for developers (Windows [®])		
POWER CONSUMPTIONS	5.5 A @ +5V; 200 mA @ +12V; 300 mA @ -12V		

Tab. 4.1: Specification table

5 Packaging and Compliancy

V1742/VX1742 modules are 1-unit wide, 6U VME64/VME64X boards, EMC compliant.



Fig. 5.1: Model view



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6 Power Requirements

The table below resumes the V1742/VX1742 power consumptions per relevant power supply voltage.

MODULE	SUPPLY VOLTAGE		
	+5 V	+12 V	-12 V
V1742/VX1742	5.5 A	200 mA	300 mA
V1742B/VX1742B	5.5 A	200 mA	300 mA

Tab. 6.1: Power requirements table

7 Panels Description

V1742 and VX1742 present the same front panel structure.



Fig. 7.1: Front panels view: V1742 on the left, VX1742 on the right

Front Panel

CH[i]/TR[i]		
СНО	DESCRIPTION Analog input connectors. FUNCTION CH[i] (i = 0 to 31) receives signals from the detector. TR[i] (i = 0 to 1) receives the fast (low latency) trigger, that can possibly be digitized. MECHANICAL SPECS Series: MCX connectors. Type: CS 85MCX-50-0-16 (jack/female). Manufacturer: SUHNER Suggested plug/male: MCX-50-2-16. Suggested cable: RG174 type.	$\label{eq:spectral_spectrum} \begin{array}{l} \textbf{ELECTRICAL SPECS} \\ \mbox{Input dynamics:} \\ & 1 \ V_{pp} \ \mbox{for CH0-CH31;} \\ & 2 \ V_{pp} \ \mbox{for TR0 and TR1 (PCB Rev} \geq 1); \\ & 3 \ V_{pp} \ \mbox{for TR0 and TR1 (PCB Rev} = 0) \\ \mbox{Input impedance } (Z_{in}): 50 \ \Omega. \\ \mbox{Absolute max analog input voltage (for 1 \ V_{pp} \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $

CLK IN/CLK OUT		
	DESCRIPTION Input and output clock connectors. FUNCTION CLK-IN permits locking to an external clock reference. CLK-OUT permits propagating the clock externally. CLK-IN and CLK-OUT permit the Daisy chain of the clock signal in multi-board synchronization (A317 distribution cable available: see Tab. 2.1) ELECTRICAL SPECS Signal Level: differential LVDS, ECL, PECL, LVPECL, CML. Single-ended-to-differential A318 cable adapter available for CLK-IN (see Tab. 2.1). Coupling: • AC (CLK-IN); • DC (CLK-OUT). Z _{diff} : 100 Ω. Accuracy < 100 ppm.	MECHANICAL SPECS Series: AMPMODU connectors. Type: 3-102203-4 (3-pin). Manufacturer: AMP Inc. PINOUT

CLK IN LED (GREEN): indicates the external clock is enabled.

TRG-IN / TRG-OUT / S-IN DESCRIPTION ELECTRICAL SPECS TRG OUT General purpose digital I/O connectors. Signal Level: single-ended NIM/TTL, sw • selectable. FUNCTION TRG-IN/S-IN input impedance (Z_{in}): 50 Ω TRG IN TRG-OUT requires 50 Ω termination. • TRG-OUT: optionally provides out: - probes from the mezzanines; **MECHANICAL SPECS** - S-IN signal. Series: 101 A 004 connectors. S IN • TRG-IN: external trigger input. Type: DLP 101 A 004-28. • S-IN: SYNC/START/STOP configurable Manufacturer: FISCHER. input as reset of the time stamp (Sec. Alternatively: Timer Reset) or as acquisition start/stop Type: EPL 00 250 NTN. (Sec. Acquisition Run/Stop). Manufacturer: LEMO.

TTL (GREEN), NIM (GREEN): indicate the standard TTL or NIM set for TRG-OUT, TRG-IN, and S-IN.

LINK				
	DESCRIPTION Optical link port.	MECHANICAL SPECS Series: SFF Transceivers.		
LINK [®]	FUNCTION Data readout and flow control through optical link. Daisy chainable. Compliant with	Type: FTLF8519F-2KNL (LC connectors). Manufacturer: FINISAR.		
	Multimode 62.5/125 μm cable featuring LC connectors on both sides.	TX (red wrap)		
	ELECTRICAL SPECS Transfer rate: up to 80 MB/s.			

LINK LEDs (GREEN/YELOW): right LED (GREEN) indicates the network presence, while left LED (YELLOW) signals the data transfer activity.

MON / Σ DESCRIPTION Analog Monitor LEMO connector FUNCTION (not used).	ΜΟΝ / Σ	
		DESCRIPTION Analog Monitor LEMO connector FUNCTION (not used).

DIAGNOSTICS LEI	Ds
DTACK DTACK DILLOCK PILLBYPS RUN	DTACK (GREEN): indicates there is a VME read/write access to the board; PLL LOCK (GREEN): indicates the PLL is locked to the reference clock; PLL BYPS (GREEN): indicates the PLL drives directly the ADCs. PLL circuit is switched off and PLL LOCK LED is turned off (<i>not used</i>); RUN (GREEN): indicates the acquisition is running (data taking); TRG (GREEN): indicates the trigger is accepted;
S TRG	DRDY (GREEN): indicates the event/data is present in the Output Buffer; BLISY (BED): indicates the board is either in Dead Time condition during the analog-to-digital
ORDY	conversion or that all the buffers are full for at least one channel.
BUSY	



LVDS I/O LEDs (GREEN): Each LED close to a 4-pin group lights on if the pins are set as outputs.

IDENTIFYING LAB	ELS
CAEN Mod. V1742 (32+2)CH 12BIT 5GS/s Sw-Cap DIGITIZER	 TOP / BOTTOM: Manufacturer Board model Brief functional description
SN	BOTTOM: Serial Number (S/N)

Internal Components



Fig. 7.2: Rotary and dip switches location

Α	SW3, 4, 5, 6: "Base Address [31:16]"	Type : Rotary Switches	Function: Set the VME Base Address of the module
В	SW2: "CLOCK SOURCE" INT/EXT	Type : Dip Switch	Function: Selects the clock source (External or Internal)
С	SW7: "FW" BKP/STD	Type : Dip Switch	Function: Selects between the "Standard" (STD) and the "Backup" (BKP) FLASH page as the first to be read at power-on to load the FW on the FPGAs (default position is STD); see Sec. Firmware Updates

8 Functional Description

Analog Input Stage

The input dynamic is 1 V_{pp} on the single-ended MCX coaxial connectors ($Z_{in} = 50 \Omega$). In order to preserve the full dynamic range according to the polarity of the input signal (bipolar, positive unipolar, negative unipolar), it is possible to add a DC offset by means of a 16-bit DAC, which is up to \pm 1 V DC. The input bandwidth ranges from DC to 500 MHz (with 2nd order linear phase anti-aliasing low-pass filter).



Fig. 8.1: Analog input diagram

DC Offset Setting

The DC offset can optionally be set as common for a 8-channel group of the digitizer, or as individual for the 8 channels inside a group. In any case, this can be done either by a direct write at 0x1n98 register addresses (or 0x8098 for common setting), or by library function (CAENDigitizerLib -> SetChannelDCOffset), or in the readout software.

Additional Input

An additional channel is available on the TRn connector. The TRn can act as a fast trigger (refer to **Sec. TRO and TR1 Inputs**) and it can also be digitized and saved into memory. The TRn appears as the ninth channel of each group in the final readout. The TRn input dynamics is 2 V_{pp} for Mezzanine PCB revision \geq 1, and 3 V_{pp} for Mezzanine PCB revision = 0¹. The input dynamics is then attenuated by a factor of 2 (3 in the latter case) to make it compliant with the 1 V_{pp} dynamics of the other channels. The 16-bit DAC then allows the user to adjust the DC offset making the TRn suitable for positive and negative unipolar signals. The DC offset of the TRn input can be set either by writing at register address 0x1nDC, or by library function (CAENDigitizerLib -> SetGroupFastTriggerDCOffset), or in the readout software.

Domino Ring Sampling

The analog input signals are continuously sampled by the DRS4 (Domino Ring Sampler) chip² which consists of an on-chip inverter chain (domino wave circuit) generating a maximum of 5 GS/s sampling frequency; 2.5 GS/s, 1 GS/s, and 750 MS/s frequencies can be also programmed. The board has one chip per group, and each chip consists of 1024 capacitor cells per channel, which perform the analog sampling of the input (high frequency analog sampling). The record length of the acquisition is constrained by the cell number,

¹To check the PCB revision number, read bit[9] of register 0x1n88 [RD1]

²Detailed documentation of the DRS4 is available at http://drs.web.psi.ch/

and it is fixed to 1024 samples. Options 512, 256, and 136 can be selected by software to reduce the amount of data to be transferred, but all the 1024 cells are converted anyway (no dead-time reduction) The DRS4 chip continuously samples the input in a circular way (samples are overwritten) until a trigger signal stops its acquisition (holding phase). Then the cells release their capacitances at a readout frequency controlled by the FPGA (Output Mode).

The analog samples are digitized by the 12-bit ADC at a frequency of 29.296 MHz (low frequency digital sampling). The ADC output is stored by the FPGA into the Digital Memory Buffer. Data is then available for readout (for the data format refer to **Sec. Event Structure**).



Fig. 8.2: Input Diagram

The single TRn is split into the two DRS4 chips (see also **Sec. TR0 and TR1 Inputs**). Delay lines are equal in the two paths, anyway small differences in the digitized samples are possible due to differences in the chips and in the ADCs. When the digitization of the TRn is enabled, there is a double conversion that increases the dead-time from 110 µs when only the inputs are converted to 181 µs when also the TRn are converted.

TR0 and TR1 Inputs

The module features two fast trigger inputs TR0 and TR1 with extended level amplitude (NIM/LVTTL compliant); TR0 is common to group 0 (ch[7..0]) and group 1 (ch[15..8]), TR1 to group 2 (ch[23..16]) and group 3 (ch[31..24]). TRn signal can be used as external trigger (see **Sec. Trigger Management**). Moreover they can be also sampled into the DRS4s analog memory buffers for applications where high resolution timing and time analysis with a common reference signal (like a trigger or system clock) is required; this is achieved by setting bit[11]=1 at 0x8000.

IMPORTANT: The TRn input is attenuated by a factor of 2 (PCB revision \ge 1), or 3 (PCB revision 0) to make it compliant with the 1 V_{pp} dynamics of the DRS4 chip. For signals higher than 2 V_{pp} (3 V_{pp}) it is recommended to use an external attenuator.

To properly handle bipolar signals and also unipolar positive or negative signal, a 16-bit DAC allows the user to add a DC offset to TRn; offset value can be programmed via register 0x1nDC.

When the TRn signals are used as triggers they are processed by an internal comparator, whose threshold can be programmed via register 0x1nD4: when the TRn crosses the threshold, the FPGA stops the DRS4 acquisition and controls the sample digitalization. Examples of TRn DC Offset and Threshold are reported in Sec. Fast ("Low Latency") Trigger



Fig. 8.3: TRO logic block diagram



Clock Distribution

Fig. 8.4: Clock distribution diagram

The clock distribution of the module takes place on two domains: OSC-CLK and REF-CLK. OSC-CLK is a fixed 50-MHz clock provided by a local oscillator which handles both VME and Local Bus (communication between motherboard and mezzanine boards; see red traces in the above figure).

REF-CLK handles ADC sampling, trigger logic, acquisition logic (samples storage into RAM, buffer freezing on trigger) through a clock chain. REF-CLK can be either an external (via front panel signal on CLK-IN connector) or an internal (via local oscillator) source. In the latter case, OSC-CLK and REF-CLK will be synchronous (the operating mode remains the same anyway).

REF-CLK clock source selection can be done by setting SW2 on-board switch (see Sec. Internal Components):

- INT mode (default) means that REF-CLK is the 50 MHz of the local oscillator (REF-CLK = OSC-CLK);
- EXT mode means that REF-CLK is the external frequency fed on CLK-IN connector.

CLK-IN signal must be differential (LVDS, ECL, PECL, LVPECL, CML) with a jitter lower than 100 ppm. CAEN provides the A318 cable to adapt single-ended signals coming from an external clock unit into the differential CLK-IN connector.

The board mounts a phase-locked-loop (PLL) and clock distribution device, AD9510. It receives the REF-CLK (internal 50 MHz by default) and generates the sampling clock for ADCs and the mezzanine FPGA (SAMP-CLK0 and SAMPCLK1), as well as the trigger logic synchronization clock (TRG-CLK) and the output clock (CLK-OUT).

Refer to the AD9510 datasheet for more details: https://www.analog.com/media/en/technical-documentation/data-sheets/AD9510.pdf (in case the active link above does not work, copy and paste it on the internet browser)

PLL Mode

As introduced in **Sec. Clock Distribution**, the source of the REF-CLK signal (see **Fig. 8.4**) can be external on CLK-IN front panel connector or internal from the 50 MHz local oscillator. Selecting the REF-CLK source internal or external can be performed by acting on the on-board dip switch SW2 (see **Sec. Internal Components**). Selecting the external clock source, the CLK-IN front panel LED must be on (see **Sec. Front Panel**).

The following options are allowed:

- 1. 50 MHz internal clock source This is the standard operating mode, where the default AD9510 configuration does not require to be changed: OSC-CLK = REF-CLK.
- 50 MHz external clock source This external frequency does not require any change of the AD9510 configuration: CLK-IN = REF-CLK.
- 58.594 MHz external clock source In this case, the user is required to program the AD9510 dividers to lock the VCXO to REF-CLK: CLK-IN = REF-CLK.
 Please contact CAEN to receive the PLL programming file (Chap. 13).
- 4. External clock source different from 58.594 MHz In this case, the AD9510 dividers must be reprogrammed to lock the VCXO to REF-CLK: CLK-IN = REF-CLK. In principle, the allowed external frequencies are submultiples of the VCXO frequency (468.75 MHz). Please contact CAEN indicating the required reference clock frequency to check the feasibility and receive the PLL programming file (Chap. 13).

The PLL upgrade can be done through the CAENUpgrader tool **[RD2]**. If the digitizer is locked, the PLL-LOCK front panel LED must be on (see **Sec. Front Panel**).

Output Clock

The AD9510 output can be available on the front panel CLK-OUT connector (see **Chap. 7**). This option is particularly used in case of multi-board synchronization to propagate the clock reference source in Daisy Chain between boards (see **Sec. Multi-board Synchronization**).

Data Correction

The DRS4 chip needs data corrections because of the unavoidable differences in the chip construction process. The corrections are managed at software level, since the firmware on-board retrieves the raw data. There are three available corrections:

- 1. Cell Index Offset correction, which compensates the signal offset for the differences in cell amplitudes;
- 2. Sample Index Offset correction, which corrects the signal offset for a noise over the last 30 samples;
- 3. Time correction, which compensates the differences of the delay line of the chips.

The default correction tables are provided by CAEN in the memory flash of the board. Wavedump software **[RD3]** (and the underlying CAENDigitizer library **[RD4]**) then can retrieve the tables and make the appropriate corrections.

The user can leave the software automatically apply all the corrections, or decide which correction applies to which group through the CORRECTION_LEVEL function of WaveDump.

If the user wants to apply its own corrections, he/she can use the CAENDigitizer function GetCorrectionTable **[RD4]** to retrieve the default correction files from the board and modify them with his/her own values. The list of CAENDigitizer functions to be used on-line are:

- LoadDRS4CorrectionData, loads the correction parameters stored on board. The correction parameters to load depend on the operating sampling frequency.
- **DecodeEvent**, decode the event and apply the correction to data if LoadDRS4CorrectionData has been previously called.
- Enable/Disable DRS4Correction, enables/disables the data correction in the x742 series. When enabled, the data correction through the DecodeEvent function only applies if LoadDRS4CorrectionData has been previously called, otherwise the DecodeEvent runs the same, but data will be provided out not compensated.
- **GetCorrectionTables**, reads the correction tables from the x742 digitizer flash memory, related to the selected sampling frequency, and fills in a structure with the read values. In this way, the stored correction table become available for the user.

Finally, it is also possible to save the raw data and apply the corrections off-line. An example code is available in the CAENDigitizer library. To access the code, download and install the CAENDigitizer library (the prior installation of CAENVMElib **[RD5][RD6]** and CAENComm library **[RD7]** are required) and include the examples in the installation. Then access to the subfolder called "x742 DataCorrection":

C:/Program Files/CAEN/Digitizers/Library/Samples/x742_DataCorrection

Here the list of CAENDigitizer functions [RD4] to be used off-line:

- LoadCorrectionTables, loads the correction tables stored onto the board into a user defined structure.
- ApplyDataCorrection, applies the desired correction data (configured through a mask) to the raw data acquired by the user.
- GetNumEvents, gets the current number of events stored in the acquisition buffer.
- GetEventPtr, retrieves the event pointer of a specified event in the acquisition buffer.
- X742_DecodeEvent, decodes a specified event stored in the acquisition buffer writing data in Evt memory.

Cell Index Offset Correction

The analog capacitors of the DRS4 chip might have small differences between each other due to the construction processes. According to the cell index where the stop acquisition arrives, the same input signal can be reconstructed in different ways. For this reason it is required a cell amplitude calibration to compensate for the amplitude differences in the capacitors. The correction adjusts the baseline of the input (i.e. its offset).

Taking into account the internal noise of each channel, **Fig. 8.5** shows the sampled waveform on the left and the noise distribution histogram on the right, measured as the occurrence of the ADC counts. Plots are made before the correction. **Fig. 8.6** shows the same quantities after the correction. As expected, the noise in **Fig. 8.6** is flatter with no patterns, and its distribution has a smaller RMS.



Fig. 8.5: Sampled waveform (left) and noise histogram (right) before cell index offset correction



Fig. 8.6: Sampled waveform (left) and noise histogram (right) after cell index offset correction

Sample Index Offset Correction

From **Fig. 8.6** it is possible to see a fixed pattern over the last about 30 samples of the waveform. Therefore it is required to perform an additional calibration, called "Sample Index", that corrects for the latest samples.

Fig. 8.7 shows the result on the baseline after the correction, where the pattern on the latest samples has been corrected.



Fig. 8.7: Sampled waveform (left) and noise histogram (right) after sample index offset correction

Time Correction

The sampling sequence is handled by the DRS4 through 1024 physical delay lines; the unavoidable construction differences between such delay lines must be compensated through a time calibration.

Fig. 8.8 and **Fig. 8.9** show the fast trigger signal (TR0) sampled by the DRS4 chip related to Group 0 and Group 1, before and after the time correction respectively. High discrepancies can be seen before the correction, while the differences after the correction are extremely reduced.

To measure the differences between the data and the ideal time value of the DRS4 chip, the Integral Non-Linearity (INL) has been calculated and reported in **Fig. 8.10** and **Fig. 8.11** before and after the correction respectively. As expected, the INL shows a better agreement after the correction.



Fig. 8.8: Sampled TRO signal in GRO and GR1 before time correction



Fig. 8.9: Sampled TRO signal in GRO and GR1 after time correction



Fig. 8.10: INL time profile of DRS4 chips 0 and 1 before time correction



Fig. 8.11: INL time profile of DRS4 chips 0 and 1 after time correction

Acquisition Modes

Acquisition Run/Stop

The acquisition can be started and stopped in different ways, according to bit[2:0] of 0x8100 register:

- SW CONTROLLED (bits[1:0] = 00): Start and Stop take place by software command. Bit[2] = 0 means stopped, while bit[2] = 1 means running.
- S-IN CONTROLLED (bits[1:0] = 01): bit[2] = 1 arms the acquisition and the Start is issued as the S-IN signal is set high and the Stop occurs when it is set low. If bit[2] = 0 (disarmed), the acquisition is always off.
- FIRST TRIGGER CONTROLLED (bits[1:0] = 10): bit[2] = 1 arms the acquisition and the Start is issued on the first trigger pulse (rising edge) on the TRG-IN connector. This pulse is not used as a trigger; actual triggers start from the second pulse on TRG-IN. The Stop acquisition must be SW controlled (bit[2] is reset).
- LVDS I/Os CONTROLLED: this mode acts like the S-IN CONTROLLED (bits[1:0] = 01), but using the configurable features of the signals on the LVDS I/Os connector (see Sec. Front Panel LVDS I/Os).

Event Structure

The event can be read out via VMEbus or Optical Link; data format is 32-bit long word (see Fig. 8.12).

An event is structured as:

- Header (four 32-bit words)
- Data (variable size and format)

The Header is composed by four words, namely:

- **TOTAL EVENT SIZE** (bit[27:0] of 1st header word) is the total size of the event, i.e. the number of 32-bit long words to be read;
- BOARD ID (bit[31:27] of 2nd header word) is the GEO address, meaningful for VME64X modules;
- **BOARD FAIL FLAG** (bit[26] of 2nd header word), implemented from ROC FPGA firmware revision 4.5 on (reserved otherwise), is set to "1" in consequence of a hardware problem (e.g. PLL unlocking or over-temperature condition). The user can collect more information about the cause by reading at 0x8178 register address and contact CAEN Support Service if necessary (see **Chap. 13**);
- **PATTERN** (bit[23:8] 2nd header word) is the 16-bit PATTERN latched on the LVDS I/Os as the trigger arrives (VME boards only).
- **GROUP MASK** (bit[3:0] of the 2nd header word) is the mask of the groups participating in the event (e.g. GROUP 0 and GROUP 3 participating → Group Mask = 1001). This information must be used by the software to retrieve to which groups the samples belong.
- EVENT COUNTER (bit[23:0] of 3rd header word) is the trigger counter; it can count either accepted triggers only, or all triggers (according to bit[3] of 0x8100 register).
- EVENT TIME TAG (4th header word) is a 31-bit counter for the event time tag, with the 32nd bit used as roll over flag; the counter is reset when the acquisition starts or by an external signal (see Sec. Timer Reset) and it is incremented at each trigger clock hit. IMPORTANT NOTE: this time tag corresponds to the time when the event is created in the digitizer memory (so related to the readout), while not to the time the event occurred at the group (i.e. channel) level, so it does not correspond to any physical quantity. The physical time of arrival of the pulse can be read in the GROUP TRIGGER TIME TAG.

After the header, the data from the enabled groups is reported consecutively. The group data format for group 0 is reported in **Fig. 8.13**.

31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0

				_						
1 0 1 0	TOTAL EVENT SIZE			-						
BOARD ID BF RES	BOARD ID BF RES PATTERN RESERVED GROUP MASK									
RESERVED EVENT COUNTER										
	EVENT TIME TAG									
	GROUP 0 EVENT DESCRIPTION WORD									
	GROUP 0 DATA			GROUP						
	GROUP 0 TRIGGER TIME TAG			0						
	GROUP 1 EVENT DESCRIPTION WORD									
GROUP 1 DATA										
	GROUP 1 TRIGGER TIME TAG			_						
	GROUP 2 EVENT DESCRIPTION WORD									
GROUP 2 DATA										
GROUP 2 TRIGGER TIME TAG										
GROUP 3 EVENT DESCRIPTION WORD										
GROUP 3 DATA										
	GROUP 3 TRIGGER TIME TAG			ω						

Fig. 8.12: Event Format

Each group is composed by 8 channels (GROUP 0 = CHANNEL 0 - 7, GROUP 1 = CHANNEL 8 - 15, etc.) and by the special channel TRn: such signal is common to two groups; it can be used as Local Trigger or "digitized" and stored with the data for high resolution timing analysis between the ADC channels and the TRn itself (refer to **Sec. TR0 and TR1 Inputs**).



Note: TR0 (TR1) is split into the two DRS4 of the mezzanine and follows two different path (two different ADCs and two memory buffers). This might imply that the digitized samples of TRn might have small differences from one group to the other.

TRO can trigger both GROUP 0 and GROUP 1 and it is stored in both group data (referring to **Fig. 8.13** the label TRO_0 indicates that the TRO is saved into GROUP 0).

In the Group Event Description word (yellow in Fig. 8.13) the following fields are shown:

- **START INDEX CELL** (Bits[29:20]) is the index cell of the DRS4 chip, corresponding to the first sample of the event;
- **FREQ** (Bit[17:16]) is the sampling frequency of the DRS4 chip, whose options are:
 - 00 = 5 GS/s;
 - 01 = 2.5 GS/s;
 - 10 = 1 GS/s;
 - 11 = 750 MS/s.
- **TR** (Bit[12]) flag indicates whether the TRn has been digitized and it is available in the readout. Options are:
 - 0 = TRn signal not present in the readout;
 - 1 = TRn signal present in the readout.
- SIZE CH0...7 (Bit[11:0]) is the number of words to be read for the CH0...7 samples. Considering that each channel has 1024 samples, and that one sample is written in three words, "SIZE CH0...7" is 0xC00.

0 0	START INDEX	CELL	0	0 F	FREQ	0	0	0	TR		SIZE CH07			GR.EVT.DESC.
S ₀ -CH2 (low) S ₀ -CH1									S ₀ -CH0					
S ₀ -CH5 (low)		S ₀ -CH4								S ₀ -CH3		S ₀ -CH2 (high)		
	S ₀ -CH7						S ₀ -0	CH6			S ₀ -CH	5 (high)		
S _{N-1} -CH	l2 (low)		S	ы _{N-1} -С	CH1		S _{N-1} -CH0							
S _{N-1} -CH5 (low)		S _{N-1} -CH4								S _{N-1} -CH3		S _{N-1} -CH2 (high)		GROUP DATA
S _{N-1} -CH7			S _{N-1} -CH6			S _{N-1} -C⊦	15 (high)							
S ₂ -TR	D ₀ (low)		S	S₁-TR	₹00		S ₀ -TR0 ₀							
S ₅ -TR0 ₀ (low)		S ₄ -TR0 ₀								S ₃ -TR0 ₀		S ₂ -TR0 ₀ (high)		
S ₇ -TR0 ₀			S ₆ -TR0 ₀			S ₅ -TR0 ₀ (high)								
S _{N-1} -TR0 ₀				S _{N-2} -TR0 ₀ S _{N-3} -TR0 ₀ (high)										
RES GROUP TRIGGER TIME TAG							GR.TTT							

31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0

Fig. 8.13: Group Data Format

The **GROUP DATA** corresponds to the waveform samples, where each sample is reported from the lowest channel index to the highest.

If the readout of TRn is disabled, data related to such channel (light blue in **Fig. 8.13**) are not present in the event; if readout of TRn is enabled, data size related to such channel is Size TRn = (SIZE CH0...7)/8.

The **GROUP TRIGGER TIME TAG** records the Trigger arrival time into a 30-bit number (steps of 8.5 ns). This is the physical trigger information of the event.

Trigger Management

Once a trigger condition is met, the DRS4 chip stops its sampling phase and the analog capacitances are converted (holding phase) by a 12-bit ADC. There are four possible trigger sources:

- **Software Trigger** (common to all enabled groups). The trigger is issued through a software write on the relevant FPGA register. This mode is mainly used for debugging purposes.
- External Trigger (trigger on TRG-IN connector, common to all enabled groups). The TRG-IN connector accepts NIM and TTL input logic, which can be programmed via software. More details are in Sec. External Trigger.
- Fast (Low Latency) Local Trigger (trigger on TRO and TR1 connectors, common to couples of groups³). This mode is called "Fast" or "Low Latency" since the latency from the trigger arrival and the DRS4 stop acquisition is significantly reduced with respect to the External Trigger mode. See Sec. Fast ("Low Latency") Trigger.
- Self-trigger (common to couples of groups⁴), the acquisition is controlled by combinations in logic OR of the channel self-triggers. See Sec. Self-Trigger.

During the analog to digital conversion process, the board cannot handle other triggers. The corresponding dead-time is equal to $110 \,\mu$ s when only the inputs are digitized, and $181 \,\mu$ s when also the TRn are digitized. **Fig. 8.14** shows the block diagram of the 742 trigger management.



Fig. 8.14: Block diagram of Trigger management

³TR0 manages the acquisition of group 0 and group 1, while TR1 manages the acquisition of group 2 and group 3 (VME form factor only).

⁴Channels of group 0 and group 1 manages the acquisition of the two groups simultaneously, while channels of group 2 and group 3 manages the acquisition of the other two groups simultaneously (VME form factor only).

Software Trigger

Software triggers are internally produced via a software command (write access at 0x8108 register address) through VMEbus or Optical Link.

External Trigger

A TTL or NIM external signal can be provided in the front panel TRG-IN connector (configurable at 0x811C register address).

The TRG-IN signal is first processed by the mother board with a clock of about 58 MHz, and sent to the DRS4 to stop its acquisition with a latency of about 115 ns and a jitter of about 17 ns⁵. The latency of the external trigger makes this mode difficult to use at 5 GHz, where the maximum acquisition window is about 200 ns (1024 samples of 200 ps).

Fast ("Low Latency") Trigger

The trigger signal is fed into TRO and TR1 connectors, and it is common to couples of groups⁶. The TRn connector accepts signals with maximum amplitude of 2 V_{pp} in case of Mezzanine PCB revision \ge 1 (3 V_{pp} in case of Mezzanine PCB revision = 0)⁷.

IMPORTANT: The TRn input is attenuated by a factor of 2 (PCB revision \geq 1), or 3 (PCB revision 0) to make it compliant with the 1 V_{pp} dynamics of the DRS4 chip. For signals higher than 2 V_{pp} (3 V_{pp}) it is recommended to use an external attenuator.

This mode is called "Fast" or "Low Latency" since the latency from the trigger arrival and the DRS4 holding phase is reduced to about 42 ns with a jitter of about 8.5 ns. The signal on TRn is sent to a comparator with programmable threshold (no mother-board processing) whose output is sampled at about 117 MHz (twice the external trigger processing). When the TRn signal crosses the threshold, the acquisition of the DRS4 chip is stopped and the digitalization process starts.

This trigger mode is convenient for high precision timing measurements, since the TRn can be digitized as the other analog inputs and reported in the output data as channel number 8 of each group. The trigger can therefore be used as a time reference for the input. The DRS4 sampling period becomes the time jitter of the trigger with respect to an input of the same group, which can reach 200 ps in case of sampling at 5 GHz. The resolution in a time of flight measurement reaches up to 50 ps in case of signals and TRn in the same TRn group, and 100 ps for signals and TRn in different groups.



Note: TR0 (TR1) is split into the two DRS4 of the mezzanine and follows two different path (two different ADCs and two memory buffers). This might imply that the digitized samples of TRn might have small differences from one group to the other.

Since the TRn acts as an input signal, it is possible to adjust its baseline position (i.e. the 0 Volt) to cover the full scale. This permits the use of several types of signals, bi-polar, negative, and positive. A list of accepted signals is reported in **Tab. 8.1** and **8.2**. The TRn signal is then sent to a comparator that compares the TRn to the Trigger Threshold. When TRn crosses the threshold the trigger is issued.

Tab. 8.1 and **8.2** report few examples of DC Offset and Threshold values (hexadecimal / decimal) for typical signals that can be fed into the TRn connector. The reported Threshold values allow the user to trigger at half of the signal height.

An example on how to set the TRn triggering mode is reported in [RD8].

⁵The TRG-IN latency has been reduced to 115 ns from ROC firmware revision 4.07, while for firmware revisions less than 4.07 the latency was 255 ns with a jitter of about 34 ns.

⁶TRO manages the acquisition of group 0 and group 1, while TR1 manages the acquisition of group 2 and group 3 (VME form factor only). ⁷To check the PCP rovision number, read hit[0] of 0x1n98 register [PD1]

Mezzanine PCB Rev. \geq 1					
ECL signal on TBn	TRn DC Offset = 0x55A0 / 21920				
	TRn Threshold = 0x6666 / 26214				
NIM signal on TBn	TRn DC Offset = 0x8000 / 32768				
	TRn Threshold = 0x51C6 / 20934				
Negative signal on TBn: $V = 0 \div -400 mV$	TRn DC Offset = 0x8000 / 32768				
	TRn Threshold = 0x5C16 / 23574				
Negative signal on TBn: V = 0 ÷ 200mV	TRn DC Offset = 0x8000 / 32768				
	TRn Threshold = 0x613E / 24894				
Ringlar signal on TRn	TRn DC Offset = 0x8000 / 32768				
	TRn Threshold = 0x6666 / 26214				
TTL on TRn or Positive signal on TRn: V = 0 ÷ ≥	TRn DC Offset = 0xA800 / 43008				
2V	TRn Threshold = 0x6666 / 26214				
$Positive on TBn: V = 0 \div 2V$	TRn DC Offset = 0x91A7 / 37287				
	TRn Threshold = 0x6666 / 26214				

Tab. 8.1: Examples of DC Offset and Trigger Threshold (in hexadecimal / decimal) for typical signals on TRn connector. Values are valid for mezzanine PCB revision \geq 1.

Mezzanine PCB Rev. 0					
NIM signal on TBn	TRn DC Offset = 0x1000 / 4096				
	TRn Threshold = 0x717D / 29053				
Negative signal on TBp: $V = 0 \div 400 \text{m}V$	TRn DC Offset = 0x1000 / 4096				
	TRn Threshold = 0x6E72 / 28274				
Pipelar signal on TPn	TRn DC Offset = 0x1000 / 4096				
	TRn Threshold = 0x6C80 / 27776				
Positive on TBn: V = 0 : 2V	TRn DC Offset = 0x4000 / 16384				
	TRn Threshold = 0x7158 / 29016				

Tab. 8.2: Examples of DC Offset and Trigger Threshold (in hexadecimal / decimal) for typical signals on TRn connector. Values are valid for mezzanine PCB revision 0.

Self-Trigger

The self-trigger mode is available on 742 series from AMC firmware revision 0.4. In self-trigger mode each channel can self-trigger on its own input – leading edge discrimination – and logic OR combinations of the self-triggers enable the groups to acquire at the same time. In particular, channels of group 0 and channels of group 1 control the acquisition of the two groups simultaneously, while channels of group 2 and channels of group 3 control the acquisition of the other two groups simultaneously. Refer to 0x1nA8 register **[RD1]** for more details.

The DRS4 chip has two operating modes: "Transparent" and "Output". In Transparent mode (see **Fig. 8.15**), the input pulse is both sampled by the DRS4 capacitors (analog sampling) at high frequency, and made available at the output for the ADC digital sampling at a smaller rate, about 30 MHz. In transparent mode, the output stage is not a pure differential, since it has an offset and it is attenuated with respect to the signal correctly shaped. Transparent mode is the standard operating mode of the DRS4 chip, which continuously samples the input.

In Output mode (see **Fig. 8.16**), the input is no longer sampled and the capacitors hold the acquired samples and send them one at a time to the ADC at a frequency controlled by the FPGA (readout frequency). The Output mode starts when a trigger condition is met (see **Fig. 8.14**). Samples in Output mode are those available in the readout for the user and they are correctly shaped.



Fig. 8.15: Diagram showing the "Transparent Mode" functioning. The analog input is both sampled by the DRS4 capacitors (analog sampling) and made available at the output for the ADC digital sampling at a smaller rate. The output stage is distorted with respect to the Output mode.



Fig. 8.16: Diagram showing the "Output Mode" functioning. the input is no longer sampled and the capacitors hold the acquired samples and send them one at a time to the ADC at a frequency controlled by the FPGA (readout frequency). The output stage is correctly differential.

Since the Self-Trigger Logic inside the FPGA reads data from the ADC while the DRS4 chip works in Transparent mode, the Trigger Threshold has to be referred to the values read in Transparent mode itself, rather

to the values reported in Output mode.

To correctly set the threshold value, it is first required to make an acquisition in Transparent mode to visualize the waveform as sampled by the ADC.

Considering that the ADC frequency is about 30 MHz, it is important that the input can be sampled by the ADC itself. In particular, the pulse width should be greater than 30 ns, and the input frequency should be high enough to visualize some pulses.

IMPORTANT: The procedure of reading from the ADC and processing data by the FPGA introduces a latency of about 250 ns before the DRS4 holding phase. This mode is therefore not compliant with the DRS4 frequency = 5 GHz, but it can be useful when the board works at 2.5 GS/s, 1 GS/s, or 750 MS/s.

How to work with Self-Trigger

To work with the channel self-trigger feature, the board must be configured appropriately according to the following steps.

- Set the DC offset of each channel (at least those which are required to acquire) to ensure that the entire input signal is within the input dynamics of the board. To verify this, it is suggested to make acquisitions in the standard mode ("Output Mode") using the SW trigger.
- Set the board to perform the acquisition in "Transparent Mode" (set bit[13] = 1 of 0x8000 register).
- Make acquisitions in "Transparent Mode" using the SW trigger. No corrections are made in Transparent mode. For each channel of interest, check the value of the signal in this acquisition mode and choose the threshold for triggering.
- Set the threshold value for each channel of interest via 0x1n80 register, where n is the group index.
- Enable the channels of interest to generate a Channel Trigger via 0x1nA8 register.
- Set the board to perform the acquisition in "Output Mode" (set back bit[13] = 0 of 0x8000 register).

The board is so ready to acquire data when triggers are generated by the channels. Refer also to **[RD8]** for a practical example and **[RD1]** for the registers description:

Multi-board Synchronization

When multi-board systems are involved in an experiment, it is necessary to synchronize different boards. In this way, the user can acquire from N boards with Y channel each, like if they were just one board with $(N \times Y)$ channels.

While all the channels of the same board are simultaneously sampled at the same clock frequency by design, the main issue in the synchronization of a multi-board system is to have both the same ADC sampling clock and the same time reference for all boards. Clock synchronization is made through input/output daisy chain connections among the digitizers. One board must be chosen to be the "master" board, that commonly works upon its internal 50-MHz oscillator, while a specific reference clock (58.594 MHz) is propagated through each other board in the chain, called "slave". A programmable phase shift can adjust possible delays in the clock propagation. This allows to have both the same ADC sampling clock and the same time reference for all boards. Having the same time reference means that the acquisition starts/stops at the same time and that the time stamps of different boards are aligned to the same absolute time.

The user must then take care of the proper run and trigger propagation to all boards. Operating at high rates, it could be required to inhibit the acquisition for all boards while the state of one board or more is busy due to a memory full.

The steps to be performed to synchronize two or more V1742 are the following:

1. Clock synchronization.

- a Choose one "master" board and connect its CLK-OUT to the CLK-IN connector of the first "slave" board. The "CLOCK SOURCE" dip switch (see Sec. Internal Components) of the master board must be set to INT (internal).
 - Connect the CLK-OUT of the first slave board to the CLK-IN of the second slave board, and so for the other slaves. The "CLOCK SOURCE" dip switch of the slave boards must b e set to EXTERNAL. CAEN can provide A317 cables for the clock distribution.
- b Program the PLL of the master board to work with its internal 50-MHz oscillator and to provide a reference clock at 58.594 MHz on CLK-OUT connector.
 Description of the second to reacting the 52.504 MHz old to reacting the 52.504 MHz of the second to reacting the 52.504 MHz of the 52.
 - Program the PLL of the slave boards to receive the 58.594-MHz clock on CLK-IN and to provide it on CLK-OUT.
 - Contact CAEN to receive the PLL programming files (Chap. 13).
- c Configure the boards to provide the clock on TRG-OUT and check the clock delay between the boards on a digital oscilloscope; then program again the slaves to compensate for the delay. Report to CAEN the delay values to receive the PLL programming files (Chap. 13).
 NOTE: in case of fast trigger on TRn it is not required to achieve high precision in the clock alignment, since the time reference is defined by the common TRn (see next point)
- 2. Fast Trigger. To achieve high time precision in the measurement, it is recommended to use the "one to many" mode for the Fast trigger using the TRn connector (see Sec. Fast ("Low Latency") Trigger) and to digitize and save it in the data: the TRn acts as a common reference time for the channels. To ensure a precise time alignment, make sure that a common trigger is split in all the TRn by using cables of the same length.

NOTE: Use the Group Trigger Time Tag as time reference of the trigger (see **Sec. Event Structure**), while the Event Trigger Time Tag is the time when the event is composed by the FPGA.

- 3. **Run propagation**. The start of the run is made via software and it is propagated from the master board to the slaves through either TRG-OUT/S-IN daisy chain, or through the LVDS I/Os.
 - a TRG-OUT/S-IN daisy chain:
 - i Connect the TRG-OUT of the master to the S-IN of the slave, and so on.
 - ii Program the TRG-OUT to be synchronized with the start run (bit[17:16] and bit[19:18] of register 0x811C).
 - iii Program the acquisition to be controlled by S-IN (bit[2:0] of register 0x8100).
 - b LVDS I/O daisy chain:
 - i Connect the LVDS Output of the master to the LVDS Input of the slave, and so on.
 - ii Program the LVDS I/O as nRUN option of the nBUSY/nVETO mode (see Sec. Mode 2: nBUSY/nVETO).
 - iii Program the acquisition to be controlled by the LVDS I/O (bit[2:0] of register 0x8100).

The delay in the run propagation can be compensated via software.

- 4. Busy management. The acquisition of all boards should be inhibited when at least one board is busy to avoid that one board acquires while the others are busy. The system busy (logic OR of the busy of all boards) can be propagated out on the TRG-OUT connector of the last board through the following steps:
 - a Propagate the busy from the master to the slaves through the LVDS I/O connectors (refer to registers 0x811C, 0x81AO, and 0x811O).
 - b Program the TRG-OUT connector of the last slave to propagate out the OR of the busy (busy from its groups and busy from the LVDS) through register 0x811C.

The TRG-OUT signal than can be used to directly veto the TRn source before it is fed into the board, or it can be propagated to the TRG-IN connector of all boards. In the latter case the steps are as follows:

- a Use an external FAN IN/FAN OUT board to split the TRG-OUT signal.
- b Feed the fan-out output to the TRG-IN connector of all boards of the chain.
- c Program the veto from TRG-IN (refer to registers 0x8000 and 0x811C).

A detailed guide to multi-board synchronization can be found in **[RD9]**. Though it doesn't apply specifically to V1742 modules, it represents a valid reference to approach CAEN multi-board synchronization concepts and architecture. Please contact CAEN for clarifications and support (see **Chap. 13**).

Front Panel LVDS I/Os

The V1742 and VX1742 are provided with 16 general purpose programmable LVDS I/O signals. From the ROC FPGA firmware revision 3.8 on, a more flexible configuration management has been introduced, which allows these signals to be programmed in terms of direction (INPUT/OUTPUT) and function by groups of 4.

ROC FPGA FIRMWARE REVISIONS < 3.8:

In case of ROC FPGA firmware revisions < 3.8, the signals on the LVDS I/O pins are fixed (see the pinout in the table below).

Nr.	Direction	Description		
0	out	GROUP 0 Trigger Request		
1	out	GROUP 1 Trigger Request		
2	out	GROUP 2 Trigger Request		
3	out	GROUP 3 Trigger Request		
4 - 7	-	not used		
8	out	Memory Full		
9	out	Event Data Ready		
10	out	Channels Trigger		
11	out	RUN Status		
12	in	Trigger Time Tag Reset (active low)		
13	in	Memory Clear (active low)		
14	-	Reserved		
15	-	Reserved		

ROC FPGA FIRMWARE REVISIONS \geq 3.8:

THE USER MUST SET BIT[8] = 1 AT 0x811C IN ORDER TO ENABLE THE NEW LVDS I/Os CONFIGURATION MODES.

FOR THOSE USERS WHOSE SOFTWARE BASES ON THE OLD LVDS I/OS CONFIGURATION MAN-AGEMENT, THE WAVEFORM RECORDING FIRMWARE OF V1742 MAKES ALSO AVAILABLE THE OLD CONFIGURATIONS (bit[8] = 0 and bit[7:6] = 01 at 0x811C). SINCE THIS COULD BE NO LONGER GUARANTEED IN THE FUTURE, THE USER IS HEARTLY REC-OMMENDED TO TAKE THE NEW CONFIGURATION MANAGEMENT AS REFERENCE!

Configure the LVDS I/O signals as inputs or outputs by groups of 4 involves bit [5:2] at 0x811C register address:

```
Bit[2] acts on LVDS I/O[3:0]
Bit[3] acts on LVDS I/O[7:4]
Bit[4] acts on LVDS I/O[11:8]
Bit[5] acts on LVDS I/O[15:12]
```

Setting the bit to "0" enables the relevant signals in the group as INPUT, while setting it to "1" enables them as OUTPUT.

Programming the function by groups of 4 LVDS I/O signals, involves bit[15:0] at 0x81A0 register address:

- Mode 0 (bits[n+3:n] = 0000): REGISTER
- Mode 1 (bits[n+3:n] = 0001): TRIGGER
- Mode 2 (bits[n+3:n] = 0010): nBUSY/nVETO
- Mode 3 (bits[n+3:n] = 0011): LEGACY

where n = 0, 4, 8, 12.



Note: Whatever option is set, the LVDS I/Os are always latched with the trigger and the relevant status of the 16 signals is always written into the header Pattern field (see **Sec. Event Structure**) the user can then choose to read out it or not.

GROUP / FUNCTION	REGISTER	TRIGGER	nBUSY/nVETO	LEGACY
			15: nRunIn	15: reserved
	Pog[15.12]	Notused	14: reserved	14: reserved
	Reg[15.12]	NOL USEU	13: nVetoIn	13: reserved
			12: nBusyIn	12: nClear_TTT
			11: nRunIn	11: reserved
	Bog[11:9]	Noturad	10: reserved	10: reserved
	Reg[11.0]	Not used	9: nVetoIn	9: reserved
			8: nBusyIn	8: nClear_TTT
			7: nRunIn	7: reserved
	Pog[7:4]	Notused	6: reserved	6: reserved
	Keg[7.4]	NOL USEU	5: nVetoIn	5: reserved
			4: nBusyIn	4: nClear_TTT
			3: nRunIn	3: reserved
	Pog[2:0]	Noturad	2: reserved	2: reserved
LVD3 IN [3.0]	neg[5.0]	Not used	1: nVetoIn	1: reserved
			0: nBusyIn	0: nClear_TTT

Tab. 8.3: Functional description of the LVDS I/O signals when configured as INPUT

GROUP / FUNCTION	REGISTER	TRIGGER	nBUSY/nVETO	LEGACY
		Not used 15: nRun 15: Run Not used 14: nTrigger 14: Trigger 13: nVeto 13: DataReady 12: nBusy 12: Busy TrigOut_Gr[3:0] 11: nRun 11: Run 10: nTrigger 10: Trigger 9: nVeto 9: DataReady 8: nBusy 8: Busy 7: nRun 7: Run	15: nRun	15: Run
	Pog[15.12]		14: Trigger	
	Reg[15.12]	NOL USEU	13: nVeto	13: DataReady
			12: nBusy	12: Busy
		TrigOut_Gr[3:0] 11: nRun 11: Run 10: nTrigger 10: Trigger 9: nVeto 9: DataRead 8: nRuoy 8: Ruoy	11: nRun	11: Run
	Pog[11.9]		10: Trigger	
	Reg[11.0]		9: DataReady	
			8: nBusy	8: Busy
LVDS OUT [7:4]	Peg[7:4] Not used 7: nRun 7: Run 6: nTrigger 6: Trig		7: nRun	7: Run
		6: Trigger		
	Reg[7.4]	NOL USEU	5: nVeto	5: DataReady
			4: nBusy	4: Busy
LVDS OUT [3:0]		Reg[3:0] TrigOut_Gr[3:0]	3: nRun	3: Run
	Pog[2:0]		2: nTrigger	2: Trigger
	Reg[3:0]		3: nVeto	1: DataReady
			0: nBusy	0: Busy

Tab. 8.4: Functional description of the LVDS I/O signals when configured as OUTPUT

Mode 0: REGISTER

Direction is INPUT: the logic level of the LVDS I/O signals can be read at 0x8118 register address. Direction is OUTPUT: the logic level of the LVDS I/O signals can be written at 0x8118 register address.

Mode 1: TRIGGER

Direction is INPUT: Not available.

Direction is OUTPUT: TrigOut_Gr[3:0] are the signals from the 8-channel groups Gr0 (CH0:CH7), Gr1 (CH8:CH15), Gr2 (CH16:CH23) and Gr3 (CH24:CH31). They can be the TR fast local triggers (all TR or the accepted TR) or the busy signals (refer to 0x8000 and 0x811C registers).

Mode 2: nBUSY/nVETO

nBusy Signal

nBusyIn (INPUT) is an active low signal which, if enabled, is used to generate the nBusy signal (OUTPUT) as below.

The Busy signal (fed out on LVDS I/Os or TRG-OUT LEMO connector) is:

Almost_Full OR Dead_Time OR (LVDS_BusyIn AND BusyIn_enable)

where

- Almost_Full indicates the filling of the Buffer Memory up to a programmable level (12-bit range) set at register address 0x816C;
- Dead_Time condition due to the analog-to-digital conversion;
- LVDS_BusyIn is available in nBUSY/nVETO configuration (see Tab. 8.4);
- BusyIn_enable is set at register address 0x8100, bit[8].

nVETO Signal

Direction is INPUT: nVETOIn is an active low signal which, if enabled (register address 0x8100, bit[9] = 1), is used to veto the generation of the common trigger propagated to the channels for the event acquisition. Direction is OUTPUT: the nVETO signal is the copy of nVETOIn.

nTrigger Signal

Direction is INPUT: reserved.

Direction is OUTPUT: nTrigger signal is the copy of the trigger signal propagated to the TRG-OUT LEMO connector or copy of the acquisition common trigger. This is selected by bit[16] of the 0x81A0 register.

nRun Signal

Direction is INPUT: nRunIn is an active low signal which can be used as Start for the digitizer (register address 0x8100, bits[1:0] = 11). It is possible to program the Start on the level or on the edge of the nRunIn signal (register address 0x8100, bit[11]).

Direction is OUTPUT: nRun signal is the inverse of the internal Run of the board.

Mode 3: LEGACY

Legacy Mode has been introduced in order the LVDS connector (properly programmed) to be able to feature the same I/O signals available in the ROC FPGA firmware revisions lower than 3.8.

nClear_TTT Signal

It is the only signal available as INPUT. It is the Trigger Time Tag (TTT) reset, like in the old configuration.

Busy Signal The Busy signal is active high and it is exactly the inverse of the nBusy signal (see Sec. Mode 2: nBUSY/nVETO).

In case register address 0x816C is set to 0x0 and the BusyIn signal is disabled, the Busy is the FULL signal present in the old configuration.

DataReady Signal The DataReady is an active high signal indicating that the board has data available for readout (the same as the DataReady front panel LED does).

Trigger Signal The active high Trigger signal is the copy of the acquisition trigger (common trigger) sent from the motherboard to the mezzanines (it is neither the signal provided out on the TRG-OUT LEMO connector nor the inverse of the signal sent to the LVDS connector).

Run Signal The Run signal is active high and represents the inverse of the nRun signal (see Sec. Mode 2: nBUSY/nVETO).

Test Pattern Generator

The FPGA can emulate the ADC and write into memory a saw tooth signal for test purposes. It can be enabled via Group Configuration register.

The following figure shows the test waveforms for even and odd groups respectively.





Fig. 8.17: FPGA test waveform

Odd channel test wave

Since an event is made up of up to 1024 samples, the test event samples only a "portion" of the saw tooth; the start point of the sampling can be programmed via Initial Test Wave Value register; for example if this register is set to 0x0FF then the channels in the even groups sample the ramp between 255 and 1278; the channels in the odd groups instead sample the complementary value, therefore between 3840 and 2817.

Reset, Clear and Default Configuration

Global Reset

A global reset is performed at power-on of the module or can be issued via software by write access at 0xEF24 register address. By a global reset, the data from the Output Buffer are cleared, the event counters are reset and so all the board FPGAs which turn back to their default configuration. All counters are initialized to their initial state and all detected error conditions are cleared.

Memory Reset

The memory reset clears the data off the Output Buffer. It can be issued by write access at 0xEF28 register address.

Timer Reset

The timer reset allows to initialize the time tag counters (Event Time Tag and Group Trigger Time Tag). The timer reset can be issued either via software by a software clear command at 0xEF28 register address, or via hardware by sending a pulse to the front panel Trigger Time Tag Reset input (see **Sec. Front Panel LVDS I/Os**) or to the S-IN input (leading edge sensitive).

VMEBus Interface

The module is provided with a fully compliant VME64/VME64X interface, whose main features are:

- EUROCARD 9U Format
- J1/P1 and J2/P2 with either 160 pins (5 rows) or 96 (3 rows) connectors
- A24, A32 and CR-CSR address modes
- D32, BLT/MBLT, 2eVME, 2eSST data modes
- MCST write capability
- CBLT data transfers
- RORA interrupter
- Configuration ROM

Addressing Capabilities

• <u>Base address</u>: the module works in A24/A32 mode The Base Address of the module is selected through four rotary switches (see Fig. 7.2), then it is validated only with either a power-on cycle or a system reset (see Sec. Global Reset).

ADDRESS MODE	ADDRESS RANGE	NOTES
A24	[0x000000:0xFF0000]	SW3 and SW4 ignored



Fig. 8.18: A24 addressing

ADDRESS MODE	ADDRESS RANGE	NOTES
A32	[0x0000000:0xFFFF0000]	



Fig. 8.19: A32 addressing

• <u>CR/CSR address</u>: the addressing is based on the slot number taken from the relevant backplane lines. The recognised Address Modifier for this cycle is 2F. *This feature is implemented only on versions with* 160-pin connectors.

31	24	23 19	18	16 15		0
		GEO			OFFSET	

Fig. 8.20: CR/CSR addressing

Address Relocation

By bit[15:0] at register address 0xEF10, it is possible to set the board Base Address via software (valid values \neq 0). Such register allows to overwrite the rotary switches settings; its setting is enabled via bit[6] at 0xEF00 register address.

The used addresses are:



Fig. 8.21: Software relocation of base address

Data Transfer Capabilities and Events Readout

Once it is written in the memory, the event becomes available for the readout via VMEbus or Optical Link. According to the board model (**Tab. 2.1**), up to 128 or 1024 events per channel (1024 samples per event) can be stored in the digitizer digital memory.

The events are read out sequentially and completely, starting from the Header of the first available event, followed by the samples of the enabled groups as reported in **Fig. 8.12**. It is not possible to read out an event partially.

The size of the event (EVENT SIZE) is configurable and depends on register addresses 0x8020 **[RD1]**, as well as on the number of enabled groups. Reducing the event size does not reduce the digitizer dead time. The board supports D32 single data readout, Block Transfer BLT32, MBLT64, CBLT32/64, 2eVME and 2eSST cycles. Theoretical maximum transfer rate is up to 70 MB/s with MBLT64 (using CAEN Bridge), up to 200 MB/s with 2eSST. Up to 80 MB/s can be achieved by direct optical link.

Block Transfer D32/D64, 2eVME and 2eSST

The Block Transfer readout mode allows to read N complete events sequentially, where N is set at register address 0xEF1C, or by using the SetMaxNumEventsBLT function of the CAENDigitizer library **[RD4]**.

When developing programs, the readout process can be implemented on different basis:

- Using Interrupts: as soon as the programmed number of events is available for readout, the board. sends an interrupt to the PC over the optical communication link (not supported by USB).
- Using Polling (interrupts disabled): by performing periodic read accesses to a specific register of the board it is possible to know the number of events present in the board and perform a BLT read of the specific size to read them out.
- Using Continuous Read (interrupts disabled): continuous data read of the maximum allowed size (e.g. total memory size) is performed by the software without polling the board. The actual size of the block read is determined by the board that terminates the BLT access at the end of the data, according to the configuration of 0xEF1C register address, or the SetMaxNumEventsBLT library function mentioned above. If the board is empty, the BLT access is immediately terminated and the "Read Block" function will return 0 bytes (it is the ReadData function in the CAENDigitizer Library).

Whatever the method from above, it is suggested to ask the board for the maximum of the events per block being set. Furthermore, the greater this maximum, the greater the readout efficiency, despite of a greater memory allocation required on the host station side that is actually not a real drawback, considering the features of the personal computers available on the market.

The event is configurable as indicated in the introduction of the paragraph, namely:

[Event Size] = [8*(Buffer Size)] + [16 bytes]

Then, it is necessary to perform as many cycles as required in order to readout the programmed number of events.

It is suggested to enable BERR signal during BLT32 cycles, in order to end the cycle avoiding filler readout. The last BLT32 cycle will not be completed, it will be ended by BERR after the #N event in memory is transferred (see example in the figure below).

Since some 64-bit CPU cut off the last 32- bit word of a transferred block, if the number of words composing such block is odd, it is necessary to add a dummy word (which has then to be removed via software) in order to avoid data loss. This can be achieved by setting the ALIGN64 bit (bit[5]) at 0xEF00 register address.

MBLT64 cycle is similar to the BLT32 cycle, except that the address and data lines are multiplexed to form 64 bit address and data buses.

The 2eVME allows to achieve higher transfer rates thanks to the requirement of only two edges of the two control signals (DS and DTACK) to complete a data cycle.



Fig. 8.22: Example of BLT readout

Chained Block Transfer D32/D64

The board allows to readout events from more daisy chained boards (Chained Block Transfer mode).

The technique which handles the CBLT is based on the passing of a token between the boards; it is necessary to verify that the used VME crate supports such cycles.

Several contiguous boards, in order to be Daisy chained, must be configured as "first", "intermediate" or "last" via 0xEFOC register address. A common Base Address is then defined via the same register; when a BLT cycle is executed at the address CBLT_Base + 0x0000 ÷ 0x0FFC, the "first" board starts to transfer its data, driving DTACK properly; once the transfer is completed, the token is passed to the second board via the IACKIN-IACKOUT lines of the crate, and so on until the "last" board, which completes the data transfer and asserts BERR (which has to be enabled): the Master then ends the cycle and the slave boards are rearmed for a new acquisition. If the size of the BLT cycle is smaller than the events size, the board which has the token waits for another BLT cycle to begin (from the point where the previous cycle has ended).

Single D32 Transfer

This mode allows the user to read out a word at a time, from the header (4 words) of the first available event, followed by all the words until the end of the event, then the second event is transferred. The exact sequence of the transferred words is shown in **Sec. Event Structure**.

After the 1st word is transferred, It is suggested to check the EVENT SIZE information and then do as many cycles as necessary (actually EVENT SIZE -1) in order to read the event completely.

Optical Link Access

The board houses a Daisy chainable Optical Link (communication path which uses optical fiber cables as physical transmission line) with a maximum theoretical transfer rate of 80 MB/s supported by CAEN A2818 PCI and A3818 PCIe controllers (see **Tab. 4.1**).

Each link of the CAEN Optical Controller can connect up to 8 digitizers in Daisy chain, so a maximum of 8 boards can be Daisy chained by the single-link A2818 card, while a maximum of 32 boards by the 4-link A3818 card (A3818C).

All the information on CAEN PCI/PCIe controllers can be find on CAEN website at the A2818 and A3818 pages.

The parameters for read/write accesses via Optical Link are the same used by VME cycles (Address Modifier, Base Address, data Width, etc); wrong parameter settings cause Bus Error.

Bit[3] at 0xEF00 register address allows to enable the module to broadcast an interrupt request on the Optical Link; the enabled Optical Link Controllers propagate the interrupt on the PCI bus as a request from the Optical Link is sensed. Interrupts can also be managed at the CAENDigitizer library level **[RD4]**.

VME and Optical Link accesses take place on independent paths and are handled by board internal controller, with VME having higher priority; anyway it is better to avoid accessing the board via VME and Optical Link simultaneously.



Note: CONET2 is CAEN proprietary serial protocol developed to allow the optical link communication between the host PC, equipped with a A2818 or a A3818 Controller, and a CAEN CONET slave. CONET2 is 50% more efficient in the data rate transfer than the previous CONET1 version. The two protocol versions are not compliant to each other and before to migrate from CONET1 to CONET2 it is recommended to read the instructions provided by CAEN in the dedicated Application Note **[RD10]**.

Trigger Rate

Introducing the trigger rate, it worth remarking those features which are typical of the 742 digitizer family:

- The channels can only be enabled by 8-channel groups, not individually; each group counts on a 128-event or a 1024-event memory, depending on the board model (see **Tab. 2.1**); each event is composed of a number or samples of the digitized wave which are configurable as fixed values: 1024, 520, 256, or 136 samples.
- Due to the particular architecture of the analog-to-digital conversion basing on switched-capacitors, there is a dead-time of 110 μs (if the TR fast local trigger is not digitized) or 181 μs (if TR is digitized).

The dead-time forces a "peak" trigger rate, TRG-RATE_{peak}, which is:

$$\label{eq:transformation} \begin{split} \text{TRG-RATE}_{\text{peak}} &= \frac{1}{110} \ \text{MHz} \simeq 9.09 \ \text{kHz} \ \text{if TR is not digitized;} \\ \text{TRG-RATE}_{\text{peak}} &= \frac{1}{181} \ \text{MHz} \simeq 5.525 \ \text{kHz} \ \text{if TR is digitized.} \end{split}$$

The dead-time represents the minimum time distance between a trigger event and the next one which makes the latter to be sensed and processed by the board. This means that a trigger occurring less than 110 μ s after the last one in one case and less than 181 μ s in the other will not be sensed, and the relevant event is lost (i.e. not stored in the digital memory and so not available for readout).

The "peak" trigger rate is sustainable and valid only for the first 128 events (or 1024, in case of bigger size memory), then the reference becomes the "average" trigger rate. Among the other things, the "average" trigger rate is linked to the readout and represents the average data flow supported by the board without entering the memory full condition.

The "average" trigger rate can only be computed theoretically, as it relies on the maximum transfer rate declared for the communication link being used, which is theoretical as well (i.e. guaranteed only under optimal conditions).

The board supports an Optical and a VME communication interface whose transfer rate specifications are:

- 80 MB/s for the Optical Link;
- 70 MB/s for the VME Link.

Basically, the "average" trigger rate depends on multiple factors like the number of enabled channels, the size of the acquired wave, as well as the acquisition mode and the readout software. The optimization of the code plays a critical role in the capability of getting the "average" trigger rate the closer to its theoretical value. In this optic, applying offline all the required corrections (see **Sec. Data Correction**) can help. Even data saving is a significant point, but it is an essential function that the software is standardly demanded to support.



"Average" Trigger Rate Calculation

The "average" trigger rate can be computed by the following formula:

TRANSFER_RATE

(8.1)

where:

TRANSFER_RATE is the maximum theoretical declared for the specific communication link; EVENT_SIZE is computed upon the event data format (refer to **Sec. Event Structure**).

For a single event of a x742 digitizer, the EVENT_SIZE is made of:

- 16 bytes from the HEADER field;
- 8 bytes per enabled channel group (i.e. the sum of EVENT DESCRIPTION field and GROUP EVENT TIME TAG field);
- 3 · N_S · 4 bytes (N_S is the number of acquired samples; 1 sample is over 3 words that is to say 24 bytes).

In case the TR digitization is enabled, an adding factor of $\frac{3 \cdot N_S}{8} \cdot 4$ bytes must be considered.

The resulting EVENT_SIZE is finally:

EVENT_SIZE =
$$16 + N_G \cdot \left[8 + 3 \cdot N_S \cdot 4 + \left(\frac{3 \cdot N_S}{8} \cdot 4 \right) \right]$$
 Byte (8.2)

where N_G is the number of enabled channel groups.

The values of the theoretical "average" trigger rate, computed upon the given formulas, are reported in the following tables for $N_S = 1024$ samples.

N _G	TR Not Digitized	TR Digitized
1	6.813 kHz	6.058 kHz
2	3.409 kHz	3.030 kHz
3	2.273 kHz	2.021 kHz
4	1.705 kHz	1.516 kHz

Tab. 8.5: Theoretical "average" trigger rate values for the Optical Link

N _G	TR Not Digitized	TR Digitized
1	5.962 kHz	5.300 kHz
2	2.983 kHz	2.652 kHz
3	1.989 kHz	1.768 kHz
4	1.492 kHz	1.326 kHz

Tab. 8.6: Theoretical "average" trigger rate values for the VME Link

9 Drivers & Libraries

Drivers

To interface with the board, CAEN provides Windows[®] and Linux[®] drivers for the different types of the supported physical communication links:

• **CONET Optical Link**, managed by the A2818 (PCI) and A3818 (PCIe) cards; the driver installation packages are downloadable for free on CAEN website at the A2818 or A3818 page respectively (**login required**).



Note: For the installation of the Optical Link driver, refer to the controller User Manual [RD11][RD12].

• USB 2.0 link, managed by the V1718 USB-to-VME Bridge. The driver installation packages are downloadable for free on CAEN website at the V1718 page (login required).



Note: To install the USB Link driver, follow the instructions inside the ReadMe file included in the packet or refer to the V1718 User Manual **[RD5]**.

Libraries

CAEN libraries are a set of middleware software required by CAEN software tools for a correct functioning. These libraries, including also demo and example programs, represent a powerful base for users who want to develop customized applications for the digitizer control (communication, configuration, readout, etc.):

- CAENDigitizer [RD4] is a library of C functions specifically designed for the Digitizer families and supports both waveform recording and DPP firmware. The CAENDigitizer requires the CAENComm library, which in turn requires the CAENVMELib library.
- CAENComm library [RD7] manages the communication at low level (read and write access). The purpose of this library is to implement a common interface to the higher software layers, masking the details of the physical channel and its protocol, thus making the libraries and applications that rely on the CAENComm independent from the physical layer. The CAENComm requires the CAENVMELib library (access to the VME bus), even in the cases where the VME is not used.

Installation packages are available for free download on CAEN web site (www.caen.it) at each library page (login required).

WHEN TO INSTALL CAEN LIBRARIES:

WINDOWS® compliant CAEN software = NOT. CAEN software for Windows® are stand-alone, which means the program locally installs the DLL files of the required libraries.

LINUX® compliant CAEN software = YES. CAEN software for Linux[®] is not stand-alone. The user must install the required libraries apart to run the software.

WINDOWS® and LINUX® compliant customized software = YES. The user must install the required libraries apart in case of custom software development.

CAENComm (and so the CAENDigitizer) supports the following communication channels (Fig. 9.1): PC \rightarrow USB \rightarrow V1718/VX1718 \rightarrow VMEbus \rightarrow V1742/VX1742 PC \rightarrow PCI/PCIe \rightarrow A2818/A3818 \rightarrow CONET \rightarrow V1742/VX1742 PC \rightarrow PCI/PCIe \rightarrow A2818/A3818 \rightarrow CONET \rightarrow V2718/VX2718 \rightarrow VMEbus \rightarrow V1742/VX1742



Fig. 9.1: Drivers and software layers

10 Software Tools

CAEN provides software tools to interface the 742 digitizer family, which are available for free download on CAEN web site (*http://www.caen.it*) in the software and firmware product pages (**login required**).

CAENUpgrader

CAENUpgrader is a software composed of command line tools together with a Java Graphical User Interface. With a x742 digitizer, CAENUpgrader allows in few easy steps to:

- Upgrade the FPGA firmware of the board
- Read the FPGA firmware release of the board and the bridge (if in the communication chain)
- Load a programming file to configure the internal PLL
- Get the Board Info file

CAEN Upgrader GUI - Upgrade CAEN Front-End Hardware			
Available actions Upgrade Firmware Board Model V1742 Firmware binary file nloads\x742_rev4.21_1.03.cfa Browse	Connection Type USB LINK number Board number VME Base Address 0x 0	Config Options Standard Page Backup Page Skip Verify Upgrade	
cvUpgrade Ready			



CAENUpgrader runs on Windows[®] and Linux[®] platforms, 32 and 64-bit operating systems. User must also install the required third-party Oracle Java RE 8 u40 or higher.

The software relies on the CAENComm library (see Chap. 9).



Note: CAENUpgrader for Windows[®] is stand-alone, the user needs to install only the driver for the communication link, while the software locally installs the DLLs of the required libraries. The Linux[®] version of the software needs the required CAENVME and CAENComm libraries to be installed apart by the user.

Refer to the CAENUpgrader documentation for installation instructions and a detailed description [RD2].

CAENComm Demo

CAENComm Demo is a simple program developed in C/C++ source code and provided both with Java[™] and LabVIEW[™] GUI interface. The demo mainly allows for a full board configuration at low level by direct read/write access to the registers and may be used as a debug instrument.

👻 CAENComm Demo	_ X
	potation
Tool or Decivery	Basic Example Demo vi
	Eile Edit Yew Project Operate Iools Window Help
Connect Disconnect Germio	
Address:	CAEN II Electronic Instrumentation
Value:	
Size: 16 V bits	CONNECT DISCONNECT GET INFO CLEAR LOG
Write Read	Address: 0
Address:	Value: 0
MBLT Read	Size: 16 bit 🔹
	WRITE READ
	Address: 0
	LANOITEN V
	MBLT READ
	LabVIEV/~Evaluation Software

Fig. 10.2: CAENComm Demo Java™ and LabVIEW™ graphical interface

The Demo is included in the CAENComm library Windows® installation package only.

Refer to the CAENComm documentation for installation instructions and a detailed description [RD7].

CAEN WaveDump

WaveDump is a basic console application, with no graphics, supporting only CAEN digitizers running the waveform recording firmware. It allows the user to program a single board (according to a text configuration file containing a list of parameters and instructions), to start/stop the acquisition, read the data, display the readout and trigger rate, apply some post-processing (e.g. FFT and amplitude histogram), save data to a file and also plot the waveforms using Gnuplot third-party graphing utility (www.gnuplot.info).

WaveDump is a very helpful example of C code demonstrating the use of libraries and methods for an efficient readout and data analysis. Thanks to the included source files and the VS project, starting with this demo is strongly recommended to all those users willing to write the software on their own.



Fig. 10.3: CAEN WaveDump

CAEN WaveDump runs on Windows[®] and Linux[®] platforms; Linux users are required to install the thirdparty Gnuplot.

The software relies on the CAENDigitizer and CAENComm libraries (see Chap. 9).



Note: WaveDump for Windows[®] is stand-alone, the user needs to install only the driver for the communication link, while the software locally installs the DLLs of the required libraries. The Linux[®] version of the software needs the required CAENVMELib and CAENComm libraries to be installed apart by the user.

Refer to the WaveDump documentation for installation instructions and a detailed description [RD3] [RD8].

11 HW Installation

- The V1742 fits into 6U VME crates.
- VX1742 versions require VME64X compliant crates.
- Use only crates with forced cooling air flow.
- Turn the crate OFF before board insertion/removal.
- Remove all cables connected to the front panel before board insertion/removal.

CAUTION: to manage the product, consult the operating instructions provided.



A POTENTIAL RISK EXISTS IF THE OPERATING INSTRUCTIONS ARE NOT FOLLOWED!

CAUTION: this product needs proper cooling.



USE ONLY CRATES WITH FORCED COOLING AIR FLOW SINCE OVERHEATING MAY DEGRADE THE MODULE PERFORMANCES!

CAUTION: this product needs proper handling.



THIS DIGITIZER DOES NOT SUPPORT LIVE INSERTION (HOT SWAP)! REMOVE OR INSERT THE BOARD WHEN THE CRATE IS POWERED OFF!



ALL CABLES MUST BE REMOVED FROM THE FRONT PANEL BEFORE EXTRACTING THE BOARD FROM THE CRATE!

CAEN provides the specific document "Precautions for Handling, Storage and Installation", available in the documentation tab of the product's web page, that the user is mandatory to read before to operate with CAEN equipment.

Power-on Sequence

To power on the board, perform the following steps:

- 1. Insert the V1742 into the crate;
- 2. power up the crate.

Power-on Status

At power-on, the module is in the following status:

- the Output Buffer is cleared;
- registers are set to their default configuration.

After the power-on, only the NIM and PLL LOCK LEDs must stay on (see Fig. 11.1).



Fig. 11.1: Front panel LEDs status at power-on

12 Firmware and Upgrades

The board hosts one FPGA on the mainboard and one FPGA on the mezzanine (i.e. one FPGA manages 16+1 channels). The channel FPGAs firmware is identical. A unique file is provided that will update all the FPGAs at the same time.

ROC FPGA MAINBOARD FPGA (Readout Controller + Communication Interface):

FPGA Altera Cyclone EP1C20.

AMC FPGA MEZZANINE FPGA (ADC readout/Memory Controller):

FPGA Altera Cyclone EP3C16

The firmware is stored onto the on-board FLASH memory. Two copies of the firmware are stored in two different pages of the FLASH, referred to as Standard (STD) and Backup (BKP). In case of waveform recording firmware, the board is delivered equipped with the same firmware version on both pages.

At power-on, a microcontroller reads the FLASH memory and programs the module automatically loading the first working firmware copy, that is the STD one by default in normal operating.

The on-board dedicated SW7 dip switch (see **Sec. Internal Components**) allows to select the first FLASH page to be read at power-on (STD by default).

It is possible to upgrade the board firmware via VMEbus or Optical Link by writing the FLASH with the CAENUpgrader software (see **Chap. 10**).

IT IS STRONGLY SUGGESTED TO OPERATE THE DIGITIZER UPON THE STD COPY OF THE FIRMWARE. UPGRADES ARE SO RECOMMENDED ONLY ON THE STD PAGE OF THE FLASH. THE BKP COPY IS TO BE INTENDED ONLY FOR RECOVERY USAGE. IF BOTH PAGES RESULT COR-RUPTED, THE USER WILL NO LONGER BE ABLE TO UPLOAD THE FIRMWARE VIA VMEbus OR OPTICAL LINK AGAIN AND THE BOARD NEEDS TO BE SENT TO CAEN FOR REPAIR!

Firmware Updates

Firmware updates are available for download on CAEN web site (www.caen.it) at the digitizer page (**login** required). The waveform recording is free firmware and updates are free downloadable.

Firmware File Description

The programming file is a CFA file (CAEN Firmware Archive). It is an archiving file format that aggregates all the programming files of the same firmware kind which are compatible with the same digitizer family.

The name of the CFA file follows a general convention:

• <DIGITIZER>_rev_X.Y_W.Z.CFA for the waveform recording firmware

where:

<DIGITIZER> are all the boards that can be updated by the CFA file;

options are:

- x742 (includes x742, x742B module versions);

where x = DT5 for desktop, x = N6 for NIM, x = V1/VX1 for VME64/VME64x format;

X.Y is the major/minor revision number of the ROC FPGA;

W.Z is the major/minor revision number of the AMC FPGA.

Troubleshooting

In case of upgrade failure (e.g. STD FLASH page is corrupted), the user can try to reboot the board: after a power cycle, the system programs the board automatically from the alternative FLASH page (e.g. BKP FLASH page), if this is not corrupted as well (see **Sec. Power-on Status**). The user can so perform a further upgrade attempt on the STD page to restore the firmware copy.

BECAUSE OF AN UPGRADE FAILURE, THE SW7 DIP SWITCH POSITION MAY NOT CORRESPOND TO THE FLASH PAGE FIRMWARE COPY LOADED ON THE BOARD FPGAS

OLD FLASH MEMORIES

The STD and BKP firmware copy management by the onboard microcontroller is different in case of old versions of the digitizer motherboard, which mount a smaller size of the FLASH memory.

THE SW7 DIP SWITCH POSITION CORRESPONDS TO THE FLASH PAGE FIRMWARE COPY LOADED ON THE BOARD FPGAs

To know the size of the digitizer FLASH memory, there are two options:

- read access to the 0xF050 register ("0" means small size);
- look at the board info file generated by the Get Information function of CAENUpgrader revision 1.6.0 or higher [RD2] (FLASH TYPE = 0 means small size).

In event of an upgrade failure of the STD page occurs, the following recovery procedure can be performed:

- power off the digitizer and move the SW7 dip switch to BKP forcing the board to reboot by the BKP page of the FLASH: LED status must be as in Sec. Power-on Status;
- to check if the communication works, read out the firmware revision by the Get firmware Revision function of CAENUpgrader;
- in case of success, make a new attempt to upgrade the STD page of the FLASH with the proper programming file;
- wait until the process is successfully completed, then power off the digitizer;
- move the SW7 dip switch back to STD and power on the digitizer;
- if the LED status is like in Sec. Power-on Status, then you can normally operate the bard again.

When not connecting to the board neither by the STD nor the BKP page reboot, it is recommended to contact CAEN or to send the board back in repair (see **Chap. 13**).

13 Technical Support

CAEN makes available the technical support of its specialists for requests concerning the software and hardware. Use the support form available at the following link:

https://www.caen.it/support-services/support-form/







CAEN SpA is acknowledged as the only company in the world providing a complete range of High/Low Voltage Power Supply systems and Front-End/Data Acquisition modules which meet IEEE Standards for Nuclear and Particle Physics. Extensive Research and Development capabilities have allowed CAEN SpA to play an important, long term role in this field. Our activities have always been at the forefront of technology, thanks to years of intensive collaborations with the most important Research Centres of the world. Our products appeal to a wide range of customers including engineers, scientists and technical professionals who all trust them to help achieve their goals faster and more effectively.





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UM4279 - V1742/VX1742 User Manual rev. 8- February 05th, 2020

00103/9:V1742.MUTX/8

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